ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				terials and	Mfg Informati	on		
upplier Inform	ation													
Company name*			Company unique ID			Uı	Unique ID Authority				Response Date*			
semi											2024-04-19			
ontact Name			Title - Contact			Pl	Phone - Contact*			Email	Email - Contact*			
roduct-Env-Stewa	rds		Product Enviro Compliance			N	NA			Produ	Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*		Title - Representative			Pł	Phone - Representative*			Email	Email - Representative*			
roduct-Env-Stewa	rds		Product Enviro Compliance			N	NA			Produ	Product-Env-Stewards@onsemi.com			
Requeste	r Item Number	Mfr Item Number		Mfr Item Name		E	Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		NCV272I	DMR2G	R2R Dual Amplifie	r 3MHZ OPAMP	2	2024-04-19		MY1		30.72	mg	Each	
	Proccess Information		arminal Rasa	Alloy	STD-020 MSL Rat	ing	Dank Droces	s Body Temper	ature Max Time at Pe	aak Tampar	ratura Numb	er of Reflow Cy	plac	
			Terminal Base Alloy J-STI CU Alloy 1		STD-020 WISE Kat	ing	260	s Body Telliper	30		onds 3	er or Kerlow Cy	cies	
omments	i (511) - aimeateu	C	O Alloy	1			1400		30	Iseco	Jilus 3			
	ime at peak temperature	o during sole	doring is 10-3	RO seconds										
	on regarding material co													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provi										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.43	mg	Supplier	Silicon (Si)	7440-21-3		0.43	mg
Die Attach	0.13	mg		Epoxy resin	proprietary data		0.0032	mg
			Supplier	Silver (Ag)	7440-22-4		0.1098	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0032	mg
			Supplier	Inorganic filler	Proprietary Data		0.0032	mg
			Supplier	Dicyandiamine	461-58-5		0.0006	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0097	mg
Lead Frame	14.26	mg	Supplier	Silver (Ag)	7440-22-4		0.3565	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0143	mg
			Supplier	Iron (Fe)	7439-89-6		0.3422	mg
			Supplier	Copper (Cu)	7440-50-8		13.547	mg
Mold Compound-Black	15.22	mg		Epoxy resin	proprietary data		0.761	mg
			Supplier	Phenolic Resin	Proprietary Data		0.761	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.3044	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0761	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		13.3175	mg
Plating	0.38	mg	Supplier	Tin (Sn)	7440-31-5		0.38	mg
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5		0.3	mg